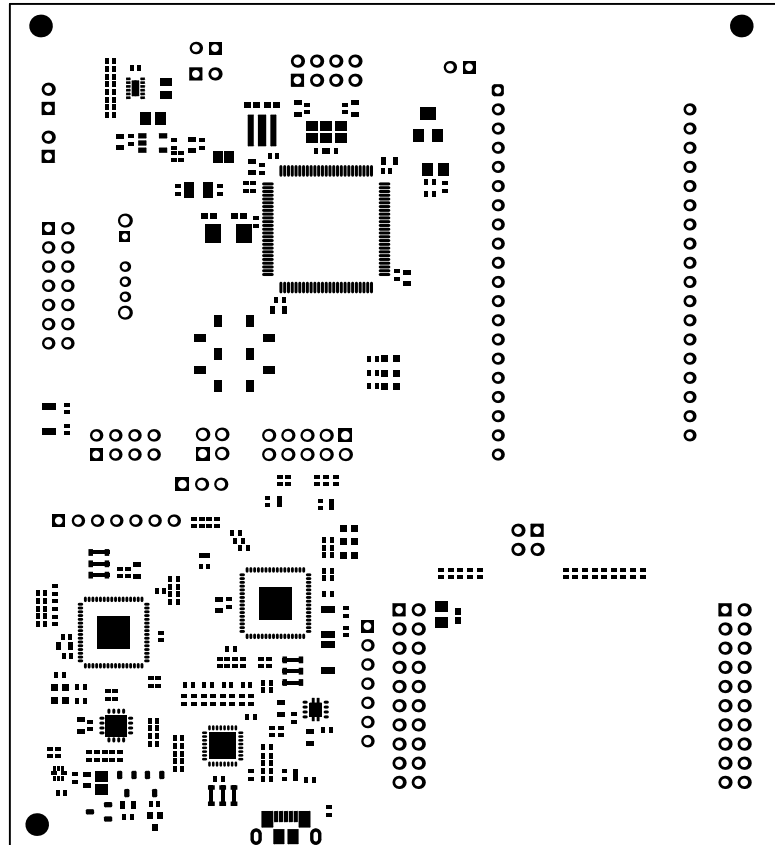
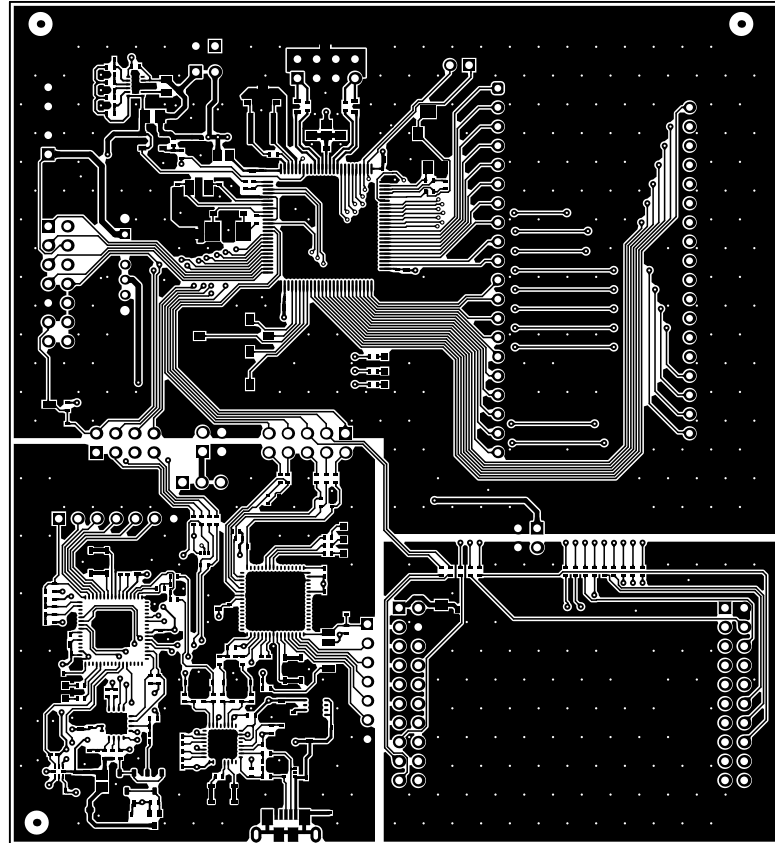


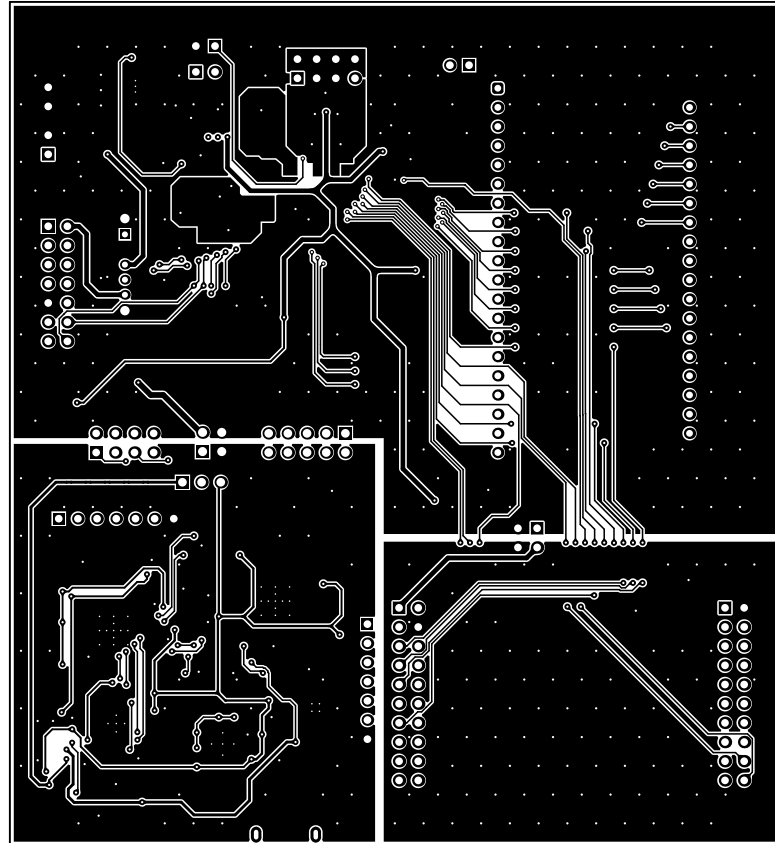
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MCU018	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Overlay	GENERATED : 4/18/2018 12:36:08 PM	TEXAS INSTRUMENTS	



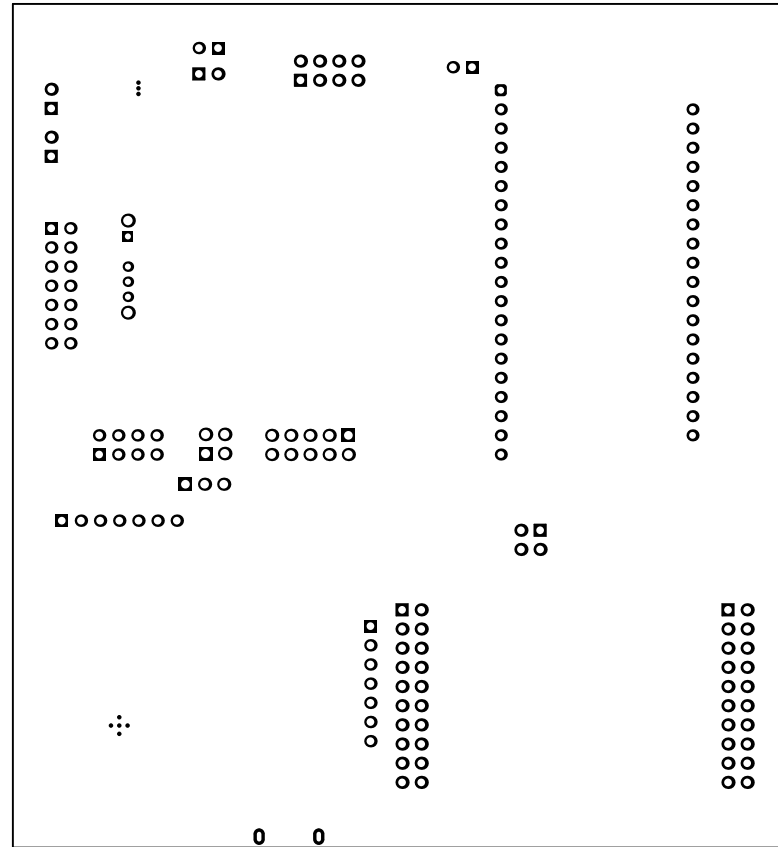
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MCU018	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask	GENERATED : 4/18/2018 12:36:09 PM	TEXAS INSTRUMENTS	



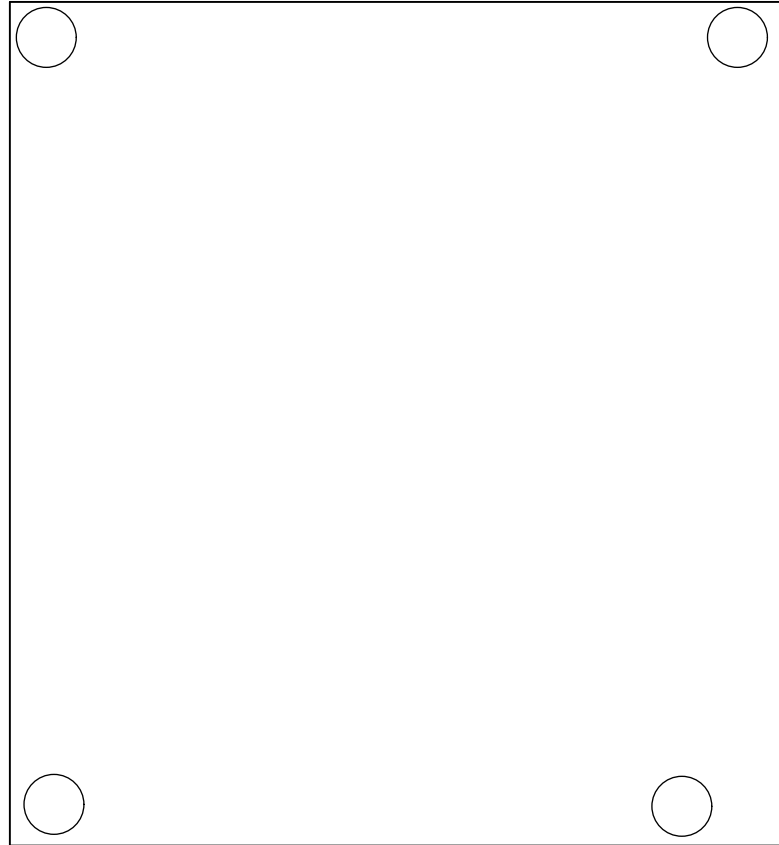
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MCU018	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 4/18/2018 12:36:10 PM	TEXAS INSTRUMENTS	



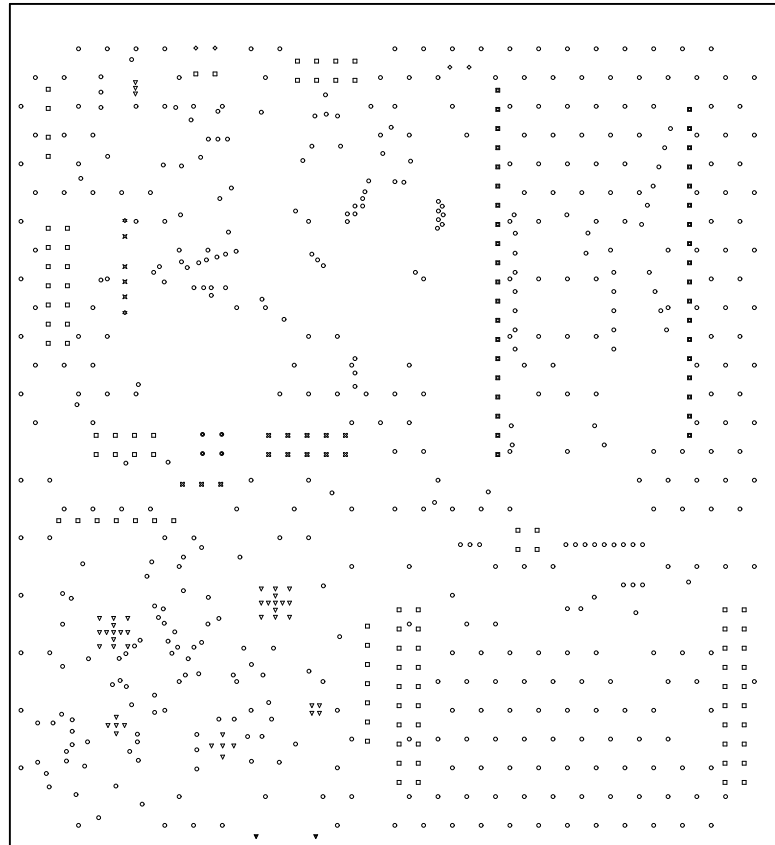
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MCU018	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 4/18/2018 12:36:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MCU018	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/18/2018 12:36:12 PM	TEXAS INSTRUMENTS	



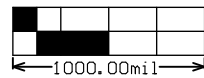
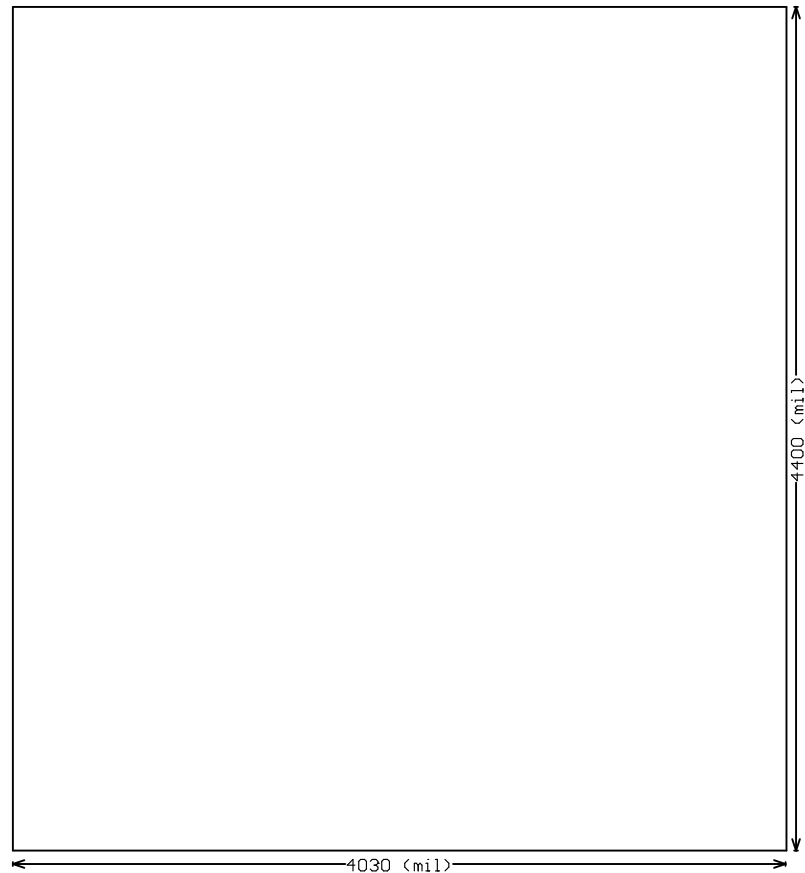
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MCU018	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Overlay	GENERATED : 4/18/2018 12:36:13 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	43	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	525	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
×	4	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
■	38	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
□	94	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
◇	4	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	13	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
●	4	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	
☆	2	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	23.62mil (0.600mm)	PTH	Slot	Top Layer - Bottom Layer	
	729 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MCU018	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing	GENERATED : 4/18/2018 12:36:14 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MCU018	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:		
PLOT NAME = Board Dimensions	GENERATED : 4/18/2018 12:36:16 PM	TEXAS INSTRUMENTS	



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